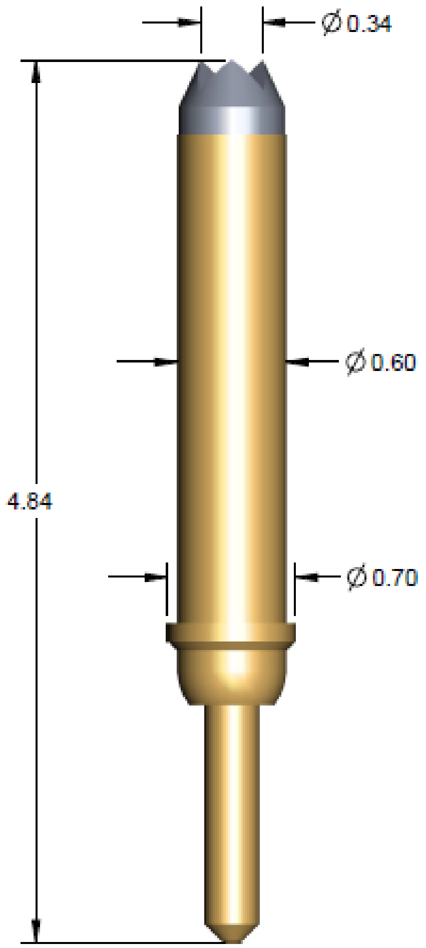
623-0195-H11 General Specifications

- **Mechanical**
  - Typical Application: BGA
  - Minimum Device Pitch: 0.8 mm
  - Work Force: 32 gf @ 0.8 mm Recommended travel
  - Operating Temperature Range: -55°C to 150°C
  - Device Side Contact: 4-point Crown Tip
  - PCB Side Contact: Conical Radius Tip
- **Electrical**
  - Loop Inductance: 0.86 nH
  - Mutual Capacitance: 0.62 pF
  - Bandwidth @ -1 dB: up to 20 GHz
  - Contact Resistance: < 50 mΩ average
  - Current Carrying Capability: 3.0 A
    - Measured in free air
- **Plating**
  - Device Side Plunger: Homogenous alloy
  - PCB Side Plunger: Gold plated
  - Barrel: Gold plated
  - Spring: Gold plated



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